RELIABILITY REPORT

FOR

MAX528EAG+

PLASTIC ENCAPSULATED DEVICES

June 15, 2010

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.

SUNNYVALE, CA 94086

Approved by
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Quality Assurance
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Conclusion

The MAX528EAG+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim"s continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim"s quality and reliability standards.

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I. Device Description

A. General

The MAX528/MAX529 are monolithic devices combining an octal 8-bit, digital-to-analog converter (DAC), 8 output buffers, and serial-interface logic in space saving shrink small outline package (SSOP). The MAX528 operates from a single supply up to 15V or from split supplies totaling up to 20V, including +5V/-15V, +12V/-5V, and +15V/-5V. The MAX529 operates from a single +5V supply or from ±5V split supplies. For both parts, a shutdown pin reduces current consumption to under 50µA, which retaining all internal DAC data. Three output modes are serially programmable for each pair of 8 analog outputs. An unbuffered mode connects the internal R-2R DAC network directly to the output pin, reducing power consumption and avoiding the buffer's DC errors. A full-buffered mode inserts a buffer between the R-2R network and the output, providing +5mA/-2mA output drive. Half-buffered output mode is similar, but uses less power while still providing up to 15mA of output drive in a unipolar output configuration. Serial data can be "daisy-chained" from one device to another. On power-up, all data bits are reset to 0, and analog outputs enter the unbuffered mode.

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II. Manufacturing Information

A. Description/Function:	Octal, Serial, 8-Bit DAC with Output Buffers
B. Process:	SG5
C. Number of Device Transistors:	
D. Fabrication Location:	Oregon
E. Assembly Location:	Malaysia, Philippines
F. Date of Initial Production:	Pre 1997

III. Packaging Information

A. Package Type:	24-pin SSOP
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive
E. Bondwire:	Au (1.3 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-0401-0380
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	125°C/W
K. Single Layer Theta Jc:	26°C/W
L. Multi Layer Theta Ja:	n/a
M. Multi Layer Theta Jc:	n/a

IV. Die Information

A. Dimensions:	220 X 126 mils
B. Passivation:	Si_3N_4/SiO_2 (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	5.0 microns (as drawn)
F. Minimum Metal Spacing:	5.0 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO_2
I. Die Separation Method:	Wafer Saw

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V. Quality Assurance Information

A. Quality Assurance Contacts: Don Lipps (Manager, Reliability Engineering)
Bryan Preeshl (Managing Director of QA)

B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.
0.1% For all Visual Defects.

C. Observed Outgoing Defect Rate: < 50 ppm

D. Sampling Plan: Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{MTTF} = \frac{8.35}{192 \times 4340 \times 414 \times 2}$$

(Chi square value for MTTF upper limit)

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$\lambda = 12.1 \times 10^{-9}$

λ = 12.1 F.I.T. (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim"s reliability monitor program. Maxim performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at http://www.maxim-ic.com/qa/reliability/monitor. Cumulative monitor data for the SG5 Process results in a FIT Rate of 0.12 @ 25C and 2.04 @ 55C (0.8 eV, 60% UCL)

B. Moisture Resistance Tests

The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

C. E.S.D. and Latch-Up Testing

The DA32 die type has been found to have all pins able to withstand a HBM transient pulse of +/-600V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of +/-250V.

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Table 1

Reliability Evaluation Test Results

MAX528EAG+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
Static Life Test (Note 1)				
	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	414	3
Moisture Testing (Note 2)				
HAST	Ta = 130°C RH = 85% Biased Time = 96hrs.	DC Parameters & functionality	77	0
Mechanical Stress (Note 2)				
Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality	77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.
Note 2: Generic Package/Process data

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